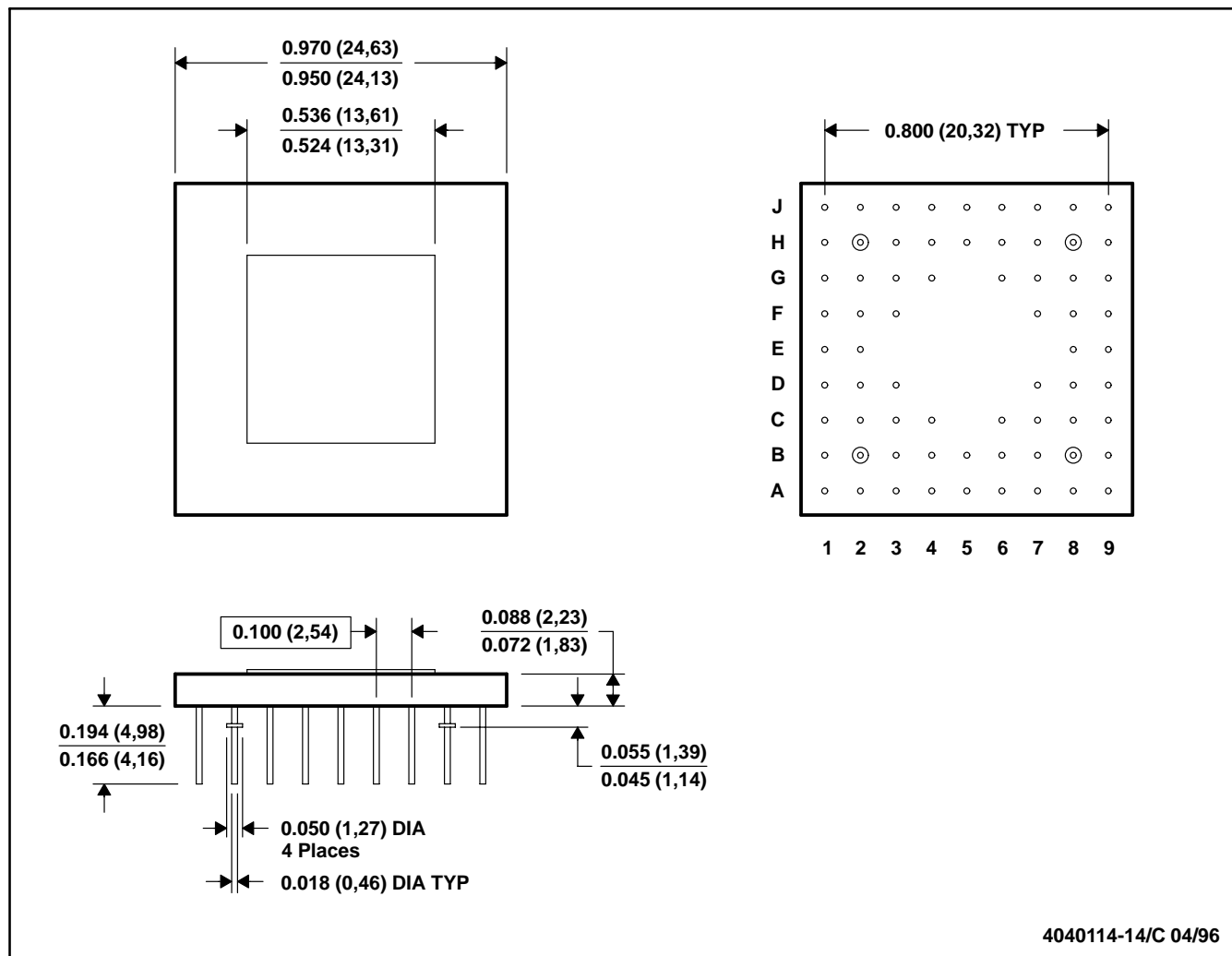


## GB (S-CPGA-P68)

## CERAMIC PIN GRID ARRAY PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Index mark may appear on top or bottom depending vendor.  
 D. Pins are located within 0.010 (0,25) diameter of true position relative to each other at maximum material condition and within 0.030 (0,76) diameter relative to the edges of the ceramic.  
 E. This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.  
 F. The pins can be gold plated or solder dipped.  
 G. Falls within MIL STD 1835 CMGA1-PN, CMGA13-PN and JEDEC MO-067 AA, MO-066 AA respectively

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